

65,536-Word-by-18-Bit High-Speed CMOS Synchronous Static RAM Preliminary

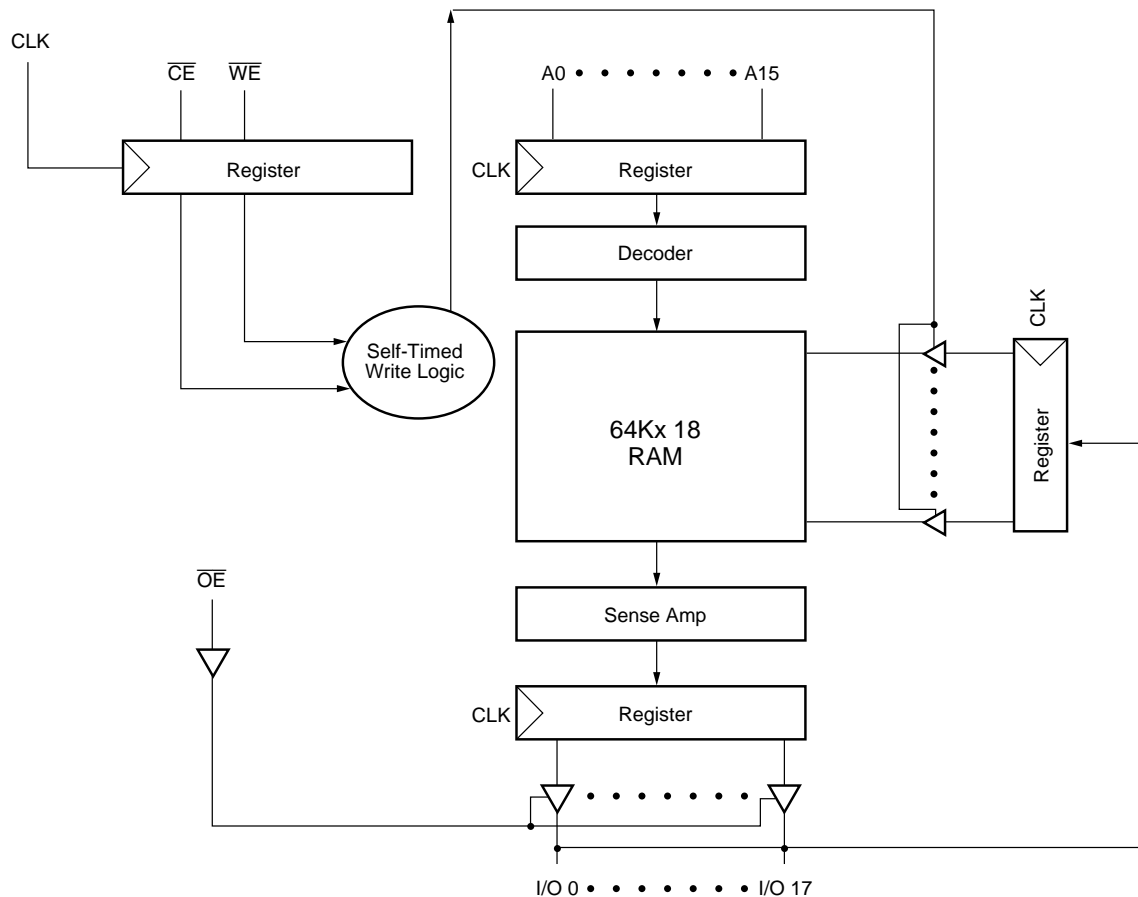
Description

The CXK77V1810GB/TM is a high-speed CMOS synchronous static RAM with common I/O pins, organized as 65,536-words-by-18-bits. This synchronous SRAM integrates input registers, high-speed SRAM and output registers onto a single monolithic IC. All input signals, except \overline{OE} , are latched at the positive edge of an external clock (CLK). The RAM data from the previous cycle is presented at the positive edge of the subsequent clock cycle. Write operation is initiated by the positive edge of CLK and is internally self-timed. This feature eliminates complex off-chip write pulse generation and provides increased flexibility for incoming signals. Asynchronous \overline{OE} adds the flexibility of data bus control. 100MHz operation is obtained from a single 3.3V power supply.

Features

- High speed, low power consumption
- Single +3.3V power supply: $3.3V \pm 5\%$
- Inputs and outputs are LVTTTL/LVCMOS-compatible
- Byte Select capability
- Asynchronous \overline{OE}
- Common data input and output
- 9ns cycle time (110MHz)
- All inputs (except \overline{OE}) and outputs are registered on a single clock edge
- Self-timed write cycle
- Package line-up:
 - GB: 7 x 17 Plastic Ball Grid Array with 50mil pitch
 - TM: 400mil, 50-pin TSOP II with .8mm pitch

Functional Block Diagram



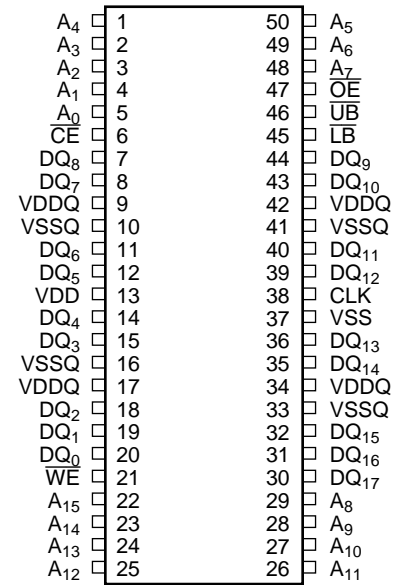
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Pin Configuration (top view)

CXK77V1810GB

CXK77V1810TM

	1	2	3	4	5	6	7
A	VDDQ	A0	A2	NC	A4	A5	VDDQ
B	NC	NC	NC	NC	NC	NC	NC
C	NC	A1	A3	VDD	A6	A7	NC
D	DQ8	NC	VSS	NC	VSS	DQ9	NC
E	NC	DQ7	VSS	\overline{CE}	VSS	NC	DQ10
F	VDDQ	NC	VSS	\overline{OE}	VSS	DQ11	VDDQ
G	NC	DQ6	\overline{LB}	NC	NC	NC	DQ12
H	DQ5	NC	VSS	NC	VSS	DQ13	NC
J	VDDQ	VDD	NC	VDD	NC	VDD	VDDQ
K	NC	DQ4	VSS	CLK	VSS	NC	DQ14
L	DQ3	NC	NC	NC	\overline{UB}	DQ15	NC
M	VDDQ	DQ2	VSS	\overline{WE}	VSS	NC	VDDQ
N	DQ1	NC	VSS	A12	VSS	DQ16	NC
P	NC	DQ0	VSS	A11	VSS	NC	DQ17
R	NC	A15	NC	VDD	NC	A8	NC
T	NC	A14	A13	NC	A10	A9	NC
U	VDDQ	NC	NC	NC	NC	NC	VDDQ



Pin Description

Symbol	Description	Symbol	Description
A0 to A15	Address input	CLK	Clock input
DQ0 to DQ8	Lower Byte Data input/output	\overline{LB}	Lower Byte enable input
DQ9 to DQ17	Upper Byte Data input/output	\overline{UB}	Upper Byte enable input
VDD	+3.3V power supply	\overline{CE}	Chip Enable input
VDDQ	+3.3 output power supply	\overline{WE}	Write Enable input
VSSQ	Output ground	\overline{OE}	Output Enable input
Vss	Ground		

Separate Vssq are available only in CXK77V1810TM.
 For proper operation, VDD ≥ VDDQ at all times, including power up.

Absolute Maximum Ratings

(Ta = +25°C, GND = 0V)

Item	Symbol	Rating	Unit
Supply voltage	VDD	-0.5 to +4.6	V
Input voltage	VIN	-0.5 to Vcc + 0.5 (4.6V max.)	V
Output voltage	Vo	-0.5 to Vcc + 0.5 (4.6V max.)	V
Allowable power dissipation	Pd	1.0	W
Operating temperature	Topr	0 to +70	°C
Storage temperature	Tstg	-55 to +150	°C
Soldering temperature • time	Tsolder	260 • 10	°C • sec

Truth Table

\overline{CE} (tn)	\overline{WE} (tn)	\overline{UB} (tn)	\overline{LB} (tn)	\overline{OE}	Mode	DQ0-17 (tn)	DQ0-17 (tn+1)	VDD Current
H	X	X	X	X	Deselect	Don't care	Hi Z	ISB
L	H	X	X	H	Read, output Hi-Z	Don't care	Hi - Z	Icc
L	H	H	H	X				
L	H	L	L	L	Read bits 0-17	Don't care	DOUT(tn)	Icc
L	H	H	L	L	Read bits 0-8	Don't care	DOUT(tn)	Icc
L	H	L	H	L	Read bits 9-17	Don't care	DOUT(tn)	Icc
L	L	L	L	X	Write bits 0-17	DIN(tn)	Hi-Z	Icc
L	L	H	L	X	Write bits 0-8	DIN(tn)	Hi-Z	Icc
L	L	L	H	X	Write bits 9-17	DIN(tn)	Hi-Z	Icc

DC Recommended Operating Conditions

(Ta = +25°C, GND = 0V)

Item	Symbol	Min.	Typ.	Max.	Unit
Supply voltage	VDD	3.15	3.3	3.45	V
Output supply voltage	VDDQ*	3.15	3.3	3.45	V
Input high voltage	VIH	2.0	—	VDD + 0.3**	V
Input low voltage	VIL	-0.3**	—	0.8	V

*VDDQ must be \leq VDD at all times, including power up.

**VIL = -1.5V min. and VIH = VDD + 1.5V for pulse width less than 5ns.

Electrical Characteristics

DC and Operating Characteristics

(VCC = 3.3V \pm 10%, GND = 0V, Ta = 0 to = +70°C)

Item	Symbol	Test Conditions	Min.	Typ*	Max.	Unit
Input leakage current	ILI	VIN = GND to VDD	-1	—	1	μ A
Output leakage current	ILO	VO = GND to VCC \overline{OE} = VIH	-1	—	1	μ A
Operating power supply current	IDD	Cycle = min. Duty = 100% IOUT = 0mA	—	—	220	mA
Standby current	ISB	$\overline{CE} \geq$ VIH Cycle = min. Duty = 100% IOUT = 0mA	—	—	150	mA
Output high voltage	VOH	IOH = -2.0mA	2.4	—	—	V
Output low voltage	VOL	IOL = 2.0mA	—	—	0.4	V

*VCC = 3.3V, Ta = +25°C

I/O Capacitance

(Ta = +25°C, f = 1MHz)

Item	Symbol	Test Conditions	Min.	Max.	Unit
Input capacitance	CIN	VIN = 0V	—	5	pF
Output capacitance	COUT	VOUT = 0V	—	7	pF

Note: These parameters are sampled and are not 100% tested.

AC Electrical Characteristics

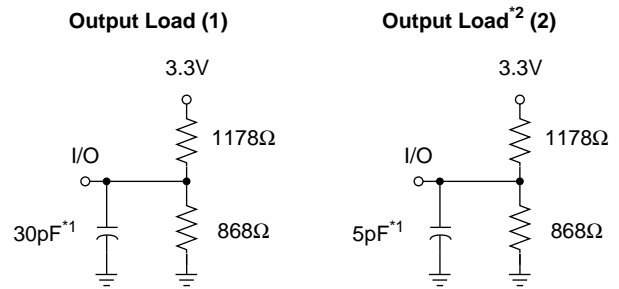
Item	Symbol	-9		-10		-12		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
Clock period	tCP	9	—	10	—	12.5	—	ns
Clock pulse high	tCH	3.5	—	4	—	4	—	ns
Clock pulse low	tCL	3.5	—	4	—	4	—	ns
Setup time	tS	2.0	—	2.5	—	2.5	—	ns
Hold time	tH	0.5	—	0.5	—	0.5	—	ns
Clock to output	tCQ	2	5.5	2	6	2	7	ns
Clock to output high impedance	tHZ*2	—	5.5	—	6	—	6	ns
Clock to output low impedance	tLZ*2	2	—	2	—	2	—	ns
\overline{OE} to output	tOE	1	5	1	5	1	6	ns
\overline{OE} to output high impedance	tOHZ*2	—	4.5	—	5	—	5	ns
\overline{OE} to output low impedance	tOLZ*2	1	—	1	—	1	—	ns

1. All parameters are specified over the range 0 to +70°C.
2. These parameters are sampled and are not 100% tested.

AC Characteristics

AC Test Conditions (VDD = 3.3V ± 5%, Ta = 0 to +70°C)

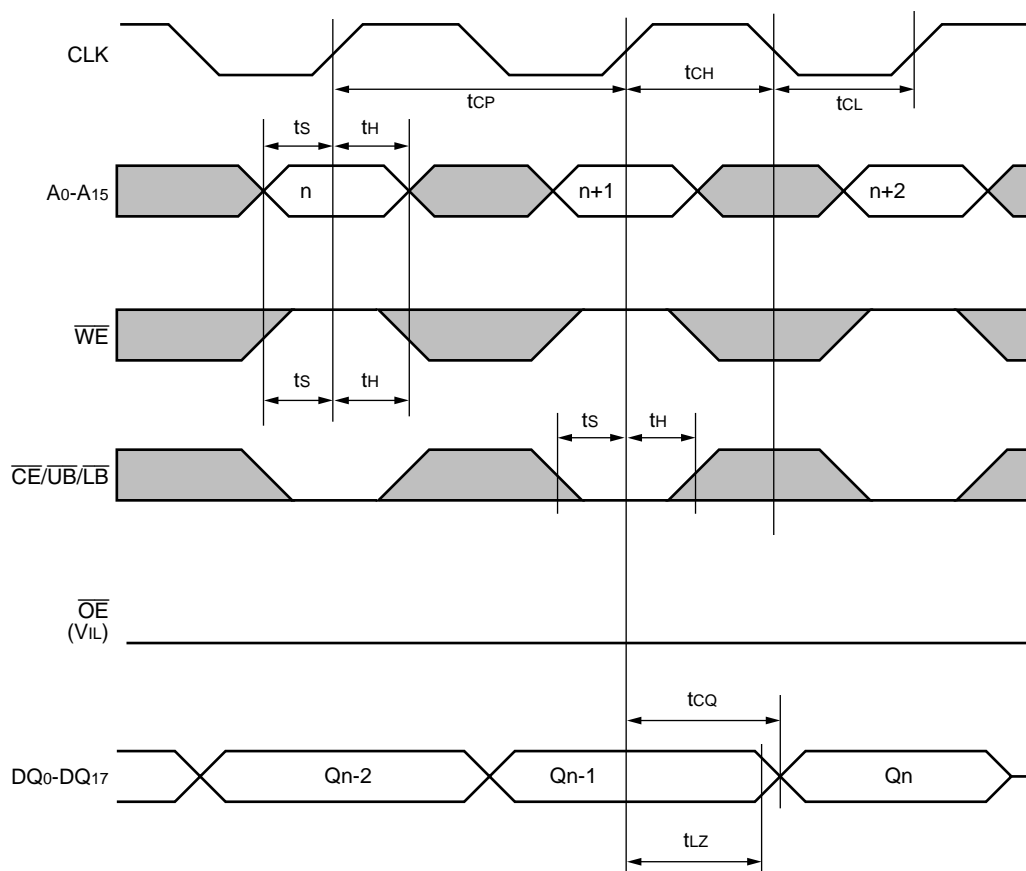
Item	Conditions
Input pulse high level	V _{IH} = 2.4V
Input pulse low level	V _{IL} = 0.4V
Input rise time	t _r = 2ns
Input fall time	t _f = 2ns
Input reference level	1.4V
Output reference level	1.4V
Output load conditions	Figure 1



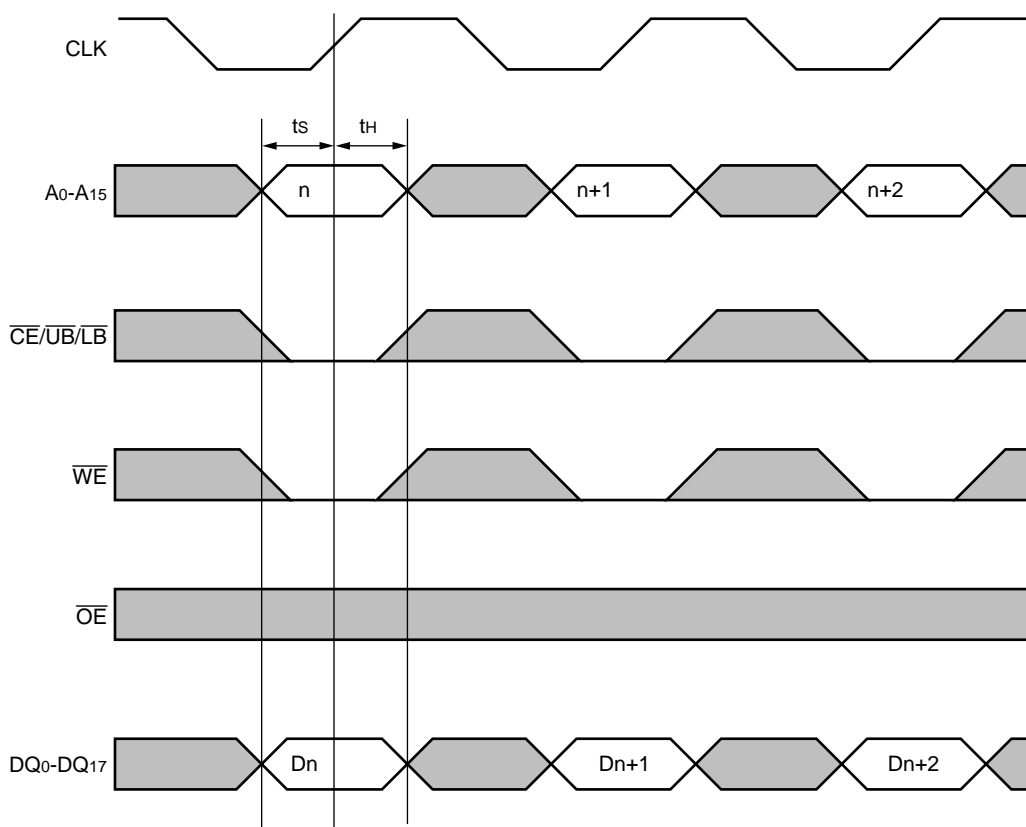
- *1. Including scope and jig capacitance.
- *2. For tLZ, tHZ

Figure 1

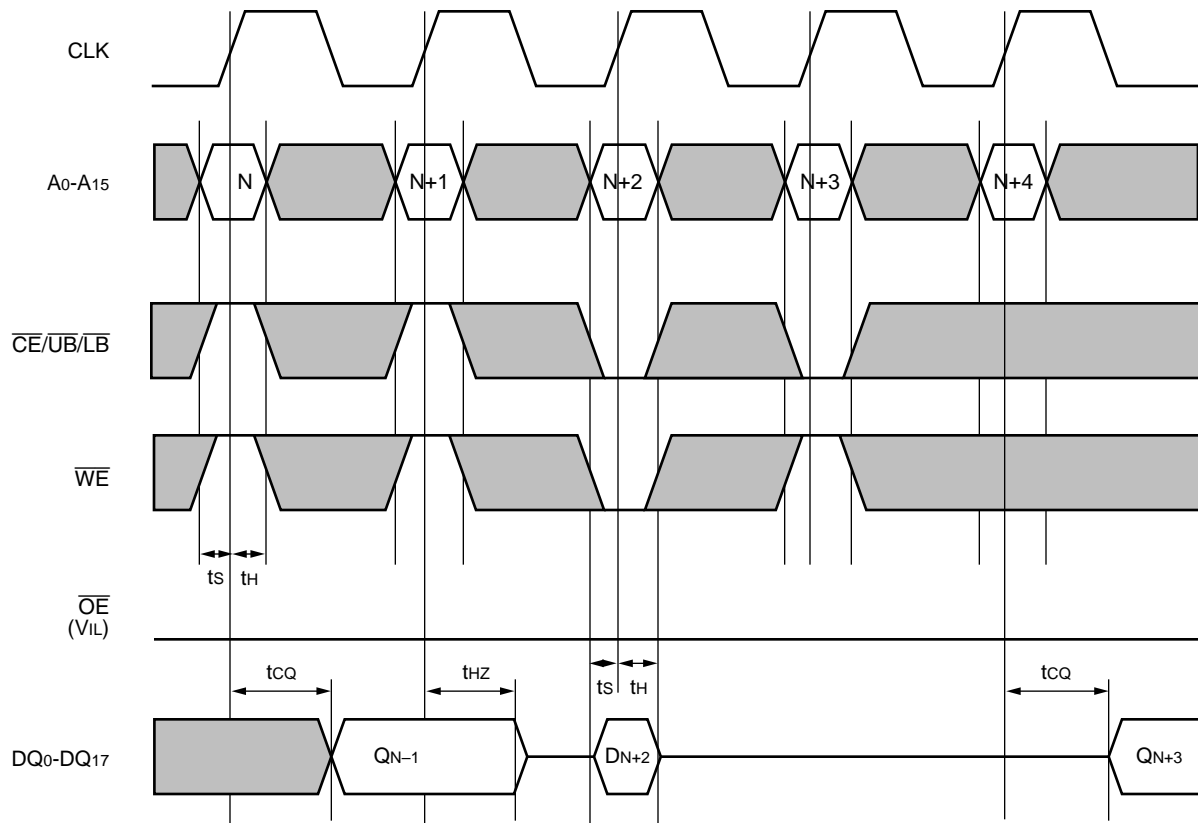
Timing Waveform of Read Cycle



Timing Waveform of Write Cycle



Timing Waveform of Read-Write-Read Cycle I ($\overline{CE}/\overline{UB}/\overline{LB}$ Control)



Timing Waveform of Read-Write-Read Cycle II (\overline{OE} Control)

